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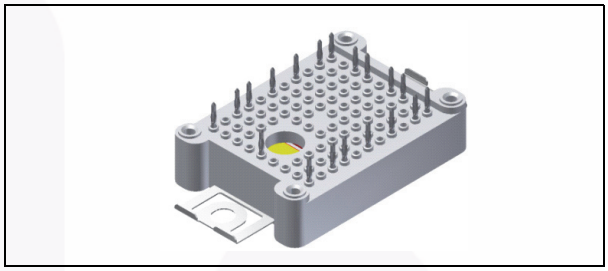
July. 2014

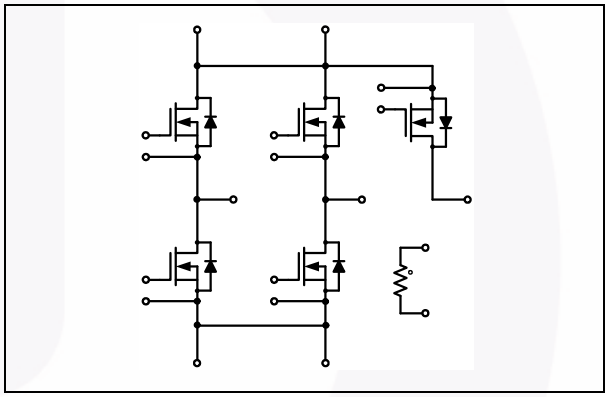
FPF1C2P5BF07A
F1 Module solution for PV-Application

General Description

Fairchild's brand-new DC-DC module is designed for a power stage that needs more compact design. And the Press-fit technology provides simple and reliable mounting. This module is optimized for the application such as solar inverter where a high efficiency and robust design are needed.



Package Code: F1



Internal Circuit Diagram

Electrical Features

- High Efficiency
- Low Conduction and Switching losses
- Low $R_{DS(ON)}$: 90 mΩ max.
- Fast Recovery Body Diode
- Built-in NTC for temperature monitoring

Mechanical Features

- Compact size : F1 Package
- Press-fit contact technology

Applications

- Solar Inverter

Certification

- UL approved (E209204)

Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Description		Rating	Units
V_{DSS}	Drain-Source Voltage		650	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	@ T_C = 25°C	36	A
		@ T_C = 80°C	27	A
I_{DM}	Pulsed Drain Current	Limited by T_J max.	156	A
I_S	Continuous Source-Drain Forward Current		36	A
I_{SM}	Maximum Pulsed Source-Drain Forward Current		156	A
P_D	Maximum Power Dissipation	@ T_C = 25°C	250	W
T_J	Operating Junction Temperature		-40 to +150	°C

Absolute Maximum Ratings T_C = 25°C unless otherwise noted. (Continued)

Symbol	Description		Rating	Units
Module				
T_{STG}	Storage Temperature		-40 to +125	°C
V_{ISO}	Isolation Voltage	@ AC 1_{MIN}	2500	V
Iso._Material	Internal Isolation Material		Al_2O_3	
F_{MOUNT}	Mounting Force per Clamp		20 to 50	N
Weight		Typ.	22	g
Creepage	Terminal to Heatshink		11.5	mm
	Terminal to Terminal		6.3	mm
Clearance	Terminal to Heatshink		10.0	mm
	Terminal to Terminal		5.0	mm

Package Marking and Ordering Information

Device	Device Marking	Package	Packing Type	Quantity / Tray
FPF1C2P5BF07A	FPF1C2P5BF07A	F1	Tray	22

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA	650	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 650 V, V_{GS}= 0 V	-	-	25	µA
I_{GSS}	Gate-Body Leakage Current, Forward	V_{GS} = 20 V, V_{DS}= 0 V	-	-	2.5	µA
On Characteristics						
$V_{GS(th)}$	Gate-Source Threshold Voltage	V_{GS} = V_{DS}, I_D= 250 µA	-	3.8	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	I_D = 27 A, V_{GS} = 10 V	-	-	90	mΩ
		I_D = 27 A, V_{GS} = 10 V @T_C = 125°C	-	135	-	mΩ
		I_D = 47 A, V_{GS} = 10 V	-	76	-	mΩ
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 380 V I_D = 27A V_{GS} = 10 V $R_{G(ON)}$ = 51 Ω $R_{G(OFF)}$ = 3 Ω Inductive Load T_C = 25 °C	-	192	-	ns
t_r	Rise Time		-	75	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	140	-	ns
t_f	Fall Time		-	13	-	ns
E_{ON}	Turn-On Switching Loss per Pulse		-	2.29	-	mJ
E_{OFF}	Turn-Off Switching Loss per Pulse		-	58	-	µJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 380 V I_D = 27 A V_{GS} = 10 V $R_{G(ON)}$ = 51 Ω $R_{G(OFF)}$ = 3 Ω Inductive Load T_C = 125 °C	-	159	-	ns
t_r	Rise Time		-	82	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	156	-	ns
t_f	Fall Time		-	13	-	ns
E_{ON}	Turn-On Switching Loss per Pulse		-	4.06	-	mJ
E_{OFF}	Turn-Off Switching Loss per Pulse		-	65	-	µJ
$Q_{g(total)}$	Total Gate Charge	V_{DS} = 380 V, V_{GS} = 0V...+10 V, I_D = 27 A	-	155	-	nC
$R_{\theta}JC$	Thermal Resistance of Junction to Case	per Chip	-	-	0.5	°C/W
Switching Characteristics : Body Diode						
V_{SD}	Source-Drain Diode Forward Voltage	I_{SD} = 27 A, V_{GS} = 0 V	-	-	1.5	V
		I_{SD} = 47 A, V_{GS} = 0 V	-	1.3	-	V
t_{rr}	Reverse Recovery Time	I_{SD} = 27 A dI_F/dt = 364 A/µs	-	109		ns
I_{rr}	Reverse Recovery Current		-	39	-	A
Q_{rr}	Reverse Recovery Charge		-	2000	-	nC
t_{rr}	Reverse Recovery Time	I_{SD} = 27A dI_F/dt = 320 A/µs @T_C = 125°C	-	179		ns
I_{rr}	Reverse Recovery Current		-	55	-	A
Q_{rr}	Reverse Recovery Charge		-	4802	-	nC
NTC						
R_{NTC}	Rated Resistance	T_C = 25°C	-	10	-	kΩ
		T_C = 100°C	-	936	-	Ω
	Tolerance	T_C = 25°C	-3	-	+3	%
P_D	Power Dissipation	T_C = 25°C	-	-	20	mW
B_{Value}	B-Constance	$B_{25/50}$	-	3450	-	K
		$B_{25/100}$	-	3513	-	K

Typical Performance Characteristic

Fig 1. On-Region Characteristics

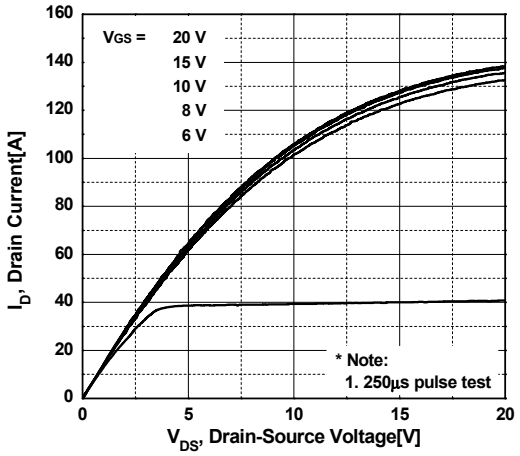


Fig 2. On-Resistance Variation vs. Drain Current and Gate Voltage

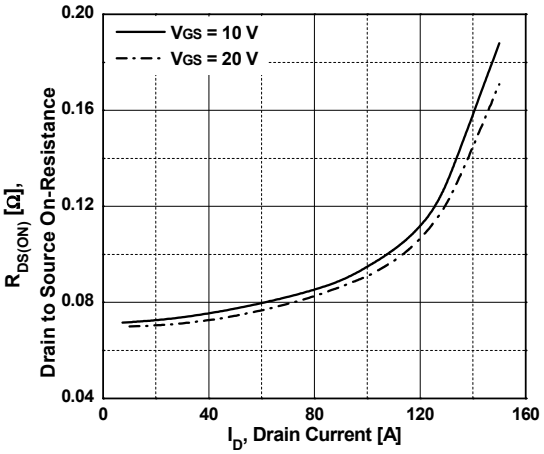


Fig 3. On-Resistance Variation vs. Temperature

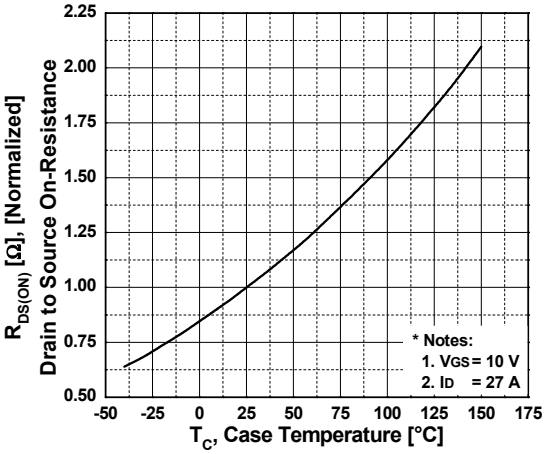


Fig 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

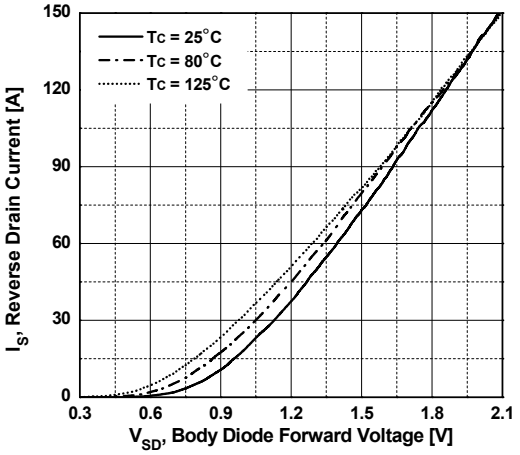


Fig 5. Turn-Off Loss vs. Drain Current

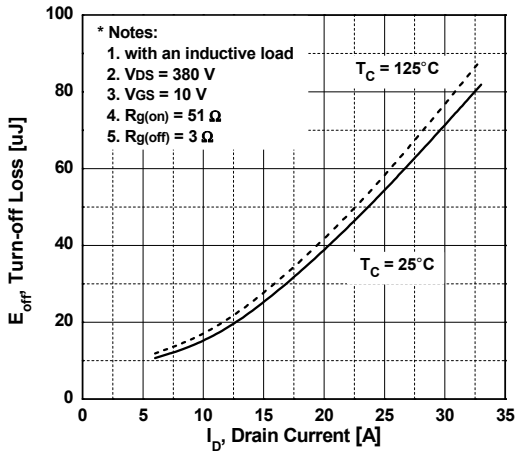
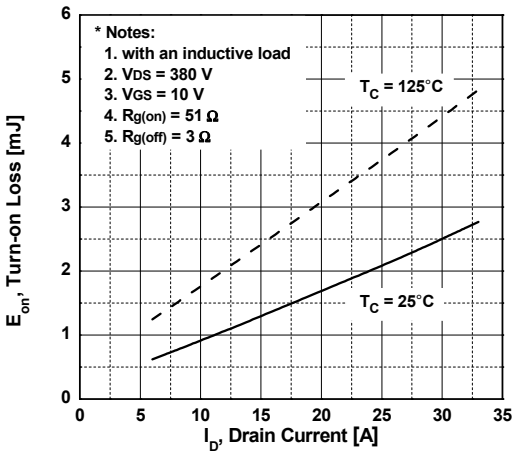


Fig 6. Turn-On Loss vs. Drain Current



Typical Performance Characteristic (Continued)

Fig 7. Turn-Off Loss vs. Turn-Off Gate Resistor Values

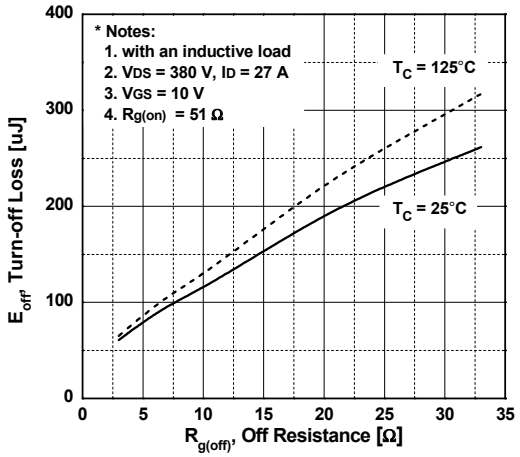


Fig 8. Transient Thermal Response Curve

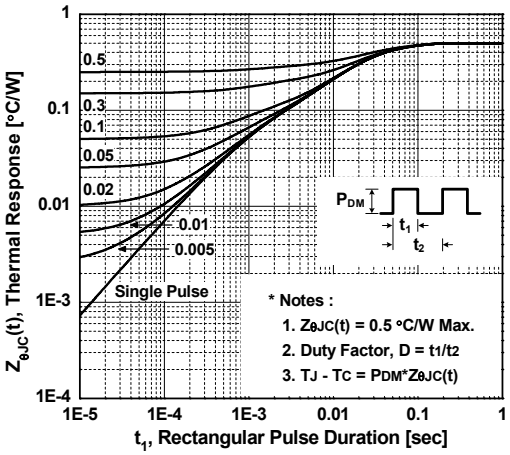
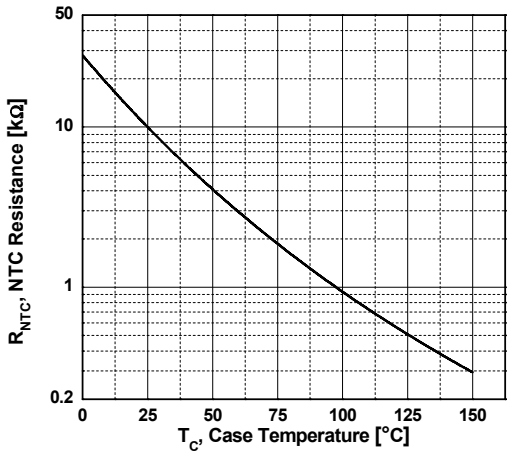
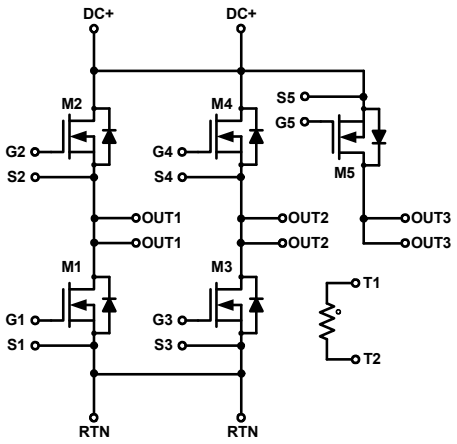


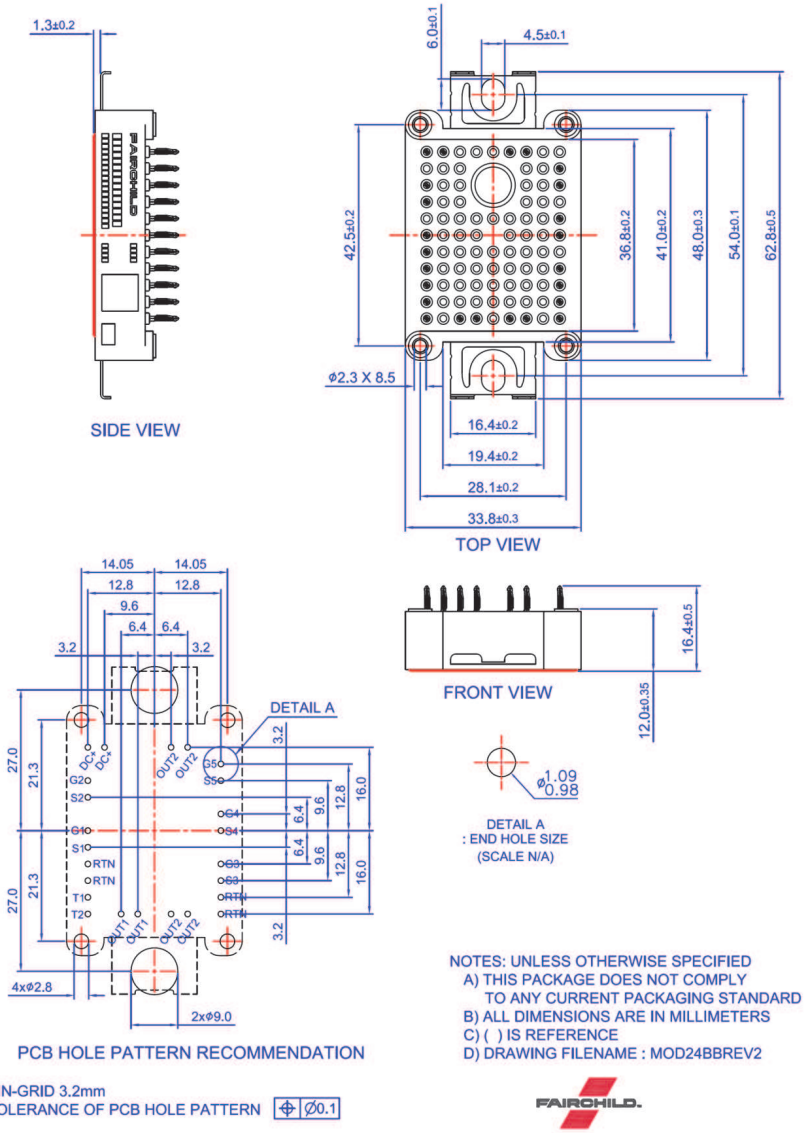
Fig 9. Typical NTC Value vs. Temperature



Internal Circuit Diagram



Package Outlines [mm]



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